1. A method of manufacturing an electronic device, comprising the steps of:

placing a positioning jig or frame having a plurality of openings on a film based substrate having adhesive paste thereon;

placing a plurality of semiconductor devices into said openings;

removing said positioning jig or frame from said film based substrate;

winding said film based substrate to form a roll; and

cutting said roll into round slices.

2. A method of manufacturing an electronic device according to Claim 1, further comprising the step of:

placing a covering sheet on said film based substrate before winding said film based substrate to form a roll.

3. A method of manufacturing an electronic device according to Claim 2, further comprising the step of:

after placing the covering sheet on the film based substrate, heating or pressuring said film based substrate and covering sheet in layer to reduce thickness before winding said film based substrate to form a roll.

4. A method of manufacturing an electronic device according to Claim 1, wherein each of said semiconductor devices is a contactless identification device and has an antenna for receiving energy and transmitting data.

5. A method of manufacturing an electronic device according to Claim 1, wherein each of said openings is a through hole or a recess.

6. A method of manufacturing an electronic device according to Claim 1, wherein the size of said openings correspond to the size of said semiconductor devices.

7. A method of manufacturing an electronic device according to Claim 1, wherein the depth of said openings is less than the thickness of said semiconductor devices.

8. A method of manufacturing an electronic device according to Claim 1, wherein placing a plurality of said semiconductor devices into said openings is done by sucking and blowing said semiconductor devices.

9. A method of manufacturing an electronic device according to Claim 1, wherein said film based substrate is paper.

10. A method of manufacturing an electronic device according to Claim 1, wherein said film based substrate is cellophane adhesive tape.

11. A method of manufacturing an electronic device according to Claim 1, wherein the thickness of said semiconductor devices is equal to or less than 30 micrometers.

12. A method of manufacturing an electronic device according to Claim 1, wherein the length of the semiconductor device is equal to or less than 0.5 millimeters.

13. An electronic device manufactured by a method according to Claim 1.

14. A method of manufacturing an electronic device, comprising the steps of:

placing a positioning jig or frame having a plurality of openings on a film based substrate having adhesive paste thereon;

placing a plurality of semiconductor devices each having a support member into said openings;

removing said positioning jig or frame from said film based substrate;

winding said film based substrate to form a roll; and

cutting said roll into round slices.

15. A method of manufacturing an electronic device according to Claim 14, further comprising the steps of:

placing a covering sheet on said film based substrate before winding said film based substrate to form a roll.

16. A method of manufacturing an electronic device according to Claim 15, further comprising the steps of:

after placing the covering sheet on said film based substrate, heating or pressuring said film based substrate and covering sheet in layer to melt said support member before winding said film based substrate to form a roll.

17. A method of manufacturing an electronic device according to Claim 14, wherein each of said semiconductor devices is a contactless identification device and has an antenna for receiving energy and transmitting data.

18. A method of manufacturing an electronic device according to Claim 14, wherein each of said openings is a through hole or a recess.

19. A method of manufacturing an electronic device according to Claim 14, wherein the size of said openings corresponds to the size of said semiconductor devices.

20. A method of manufacturing an electronic device according to Claim 14, wherein the depth of said openings is less than the thickness of said semiconductor devices.